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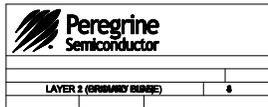
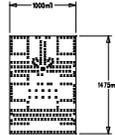
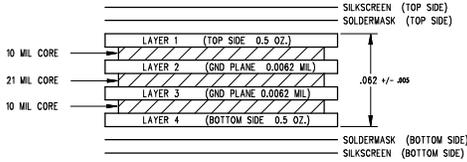
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FSCM DWG NO. SH REV

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
-	03	SILKSCREEN LABELING	1-30-12	ARMANDO

17. THIS PCB TO BE ROHS COMPLIANT IN MATERIALS AND MANUFACTURING PROCESSES.
16. PLEASE MAKE SURE PRECAUTIONS ARE TAKEN ON THIS BOARD WITH REGARDS TO OVER ETCHING.
15. ALL PEREGRINE BOARDS TO USE NETLIST COMPARISON TO VERIFY GERBER DATA PRIOR TO MANUFACTURING USING THE SUPPLIED IPC-D-356A NETLIST. REMOVE BOARD OUTLINE PRIOR TO NET COMPARE AND FAB. OK FOR RF CONNECTOR PADS TO REACH BOARD EDGE.
14. RF TRANSMISSION LINE TOLERANCE TO BE AS FOLLOWS:
50 OHMS +/- 5%.
22 MIL WIDTH 7 MIL GAP
CROSS-SECTION SHALL BE SUPPLIED WITH PARTS WITH THICKNESS OF T-LINES VERIFIED.
PCB VENDOR HAS AUTHORITY TO MODIFY RF TRACE WIDTH AND AIR GAP TO INSURE 50 OHM IMPEDANCE.
13. SURFACE MOUNT PAD SOLDER PLATING MUST BE FLAT TO A MAXIMUM OF .003" ABOVE BOARD
12. PLATE WITH 8 +/- 2 uIN MINIMUM IMMERSION GOLD OVER 175 +/- 75 uIN MINIMUM ELECTROLESS NICKEL OVER COPPER.
11. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
10. FABRICATE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
9. BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0. VENDOR'S UL LOGO OR DESIGNATION AND DATE SHALL BE LOCATED ON THE BOTTOM SIDE.
8. REMOVE ALL BURRS AND BREAK SHARP EDGES .015 MAX.
7. APPLY SILKSCREEN, AS REQUIRED, USING WHITE EPOXY INK.
6. WARP OR TWIST OF BOARD SHALL NOT EXCEED 10X.
5. APPLY SOLDERMASK LIQUID PHOTO IMAGEABLE (LPI) OVER BARE GOLD. SOLDERMASK TO BE PER IPC-SM-840, CLASS 1, COLOR: GREEN. ALL EXPOSED CONDUCTIVE SURFACES TO BE GOLD PLATED. UL SOLDERMASK DEFINED PADS ARE TO BE ALIGNED PRECISELY. NO SOLDERMASK ON U1 SMT PADS.
4. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/-10% OF ARTWORK ORIGINALS, UNLESS OTHERWISE NOTED.
3. ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE WITHIN .003". ALL HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANGULAR RING OF .003.
2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING. ALL PLATED THROUGH HOLES TO BE COPPER PLATED IN ACCORDANCE WITH MIL-C-14550. .0008" IN HOLES MINIMUM.
1. MATERIAL: ROGERS 4350 ON OUTER LAYERS AND FR-4 ON INNER LAYERS.
OVERALL BOARD THICKNESS TO BE .062 +/- .005

LAYOUT DETAIL
4 LAYER



NOTES: UNLESS OTHERWISE SPECIFIED

SIZE	QTY	SYN	PLATED	THR/PRTL	TOL
0.008	9	X	YES	THR	+/-0.003
0.037	10	□	YES	THR	+/-0.003
0.01	284	X	YES	THR	+/-0.003

QTY REQD	FROM NO.	PART OR DESCRIPTION NO.	NUMERATURE OR DESCRIPTION	MATERIAL SPECIFICATION
UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN INCHES TOLERANCES ARE FRACTIONS DECIMALS ANGLES ± .000" ± .000" ±				
CONTRACT NO.		COMPANY		
APPROVALS		DATE		
DRAWN STEVE JOHNSON		6-02-11		
CHECKED KEVIN ROBERTS		6-02-11		
ISSUED		TITLE		
NEXT ASSY		USED ON		
APPLICATION		DO NOT SCALE DRAWING		
SIZE		FSCM NO.		
C		DWG NO. 101-0593		
SCALE: NONE		REV. 03		
		SHEET 1 OF 1		

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